


MATERIAL DECLARATION SHEET



Package Type	PTVS1-(022C-026C-029C)-H			
Product Line	Semiconductor Products			
Compliance Date	26 th April 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.2054	Amorphous Silica	60676-86-0	87.000	60.00676	62.189
				Solid Epoxy Resin 1	Proprietary	4.600	0.20227	
				Solid Epoxy Resin 2	Proprietary	4.490	0.17245	
				Phenol Resin	Proprietary	2.700	1.01764	
				Carbon Black	1333-86-4	0.700	0.37376	
				Crystalline Silica	14808-60-7	0.510	0.41648	
2	Leadframe	Copper Alloy	0.0618	Copper	7440-50-8	97.433	18.30294	18.712
				Iron	7439-89-6	2.350	0.38795	
				Phosphorus	7723-14-0	0.125	0.00613	
				Zinc	7440-66-6	0.082	0.01235	
				Lead	7439-92-1	0.010	0.00238	
3	Clip	Copper Alloy	0.0314	Copper	7440-50-8	95.485	8.99224	9.514
				Silver	7440-22-4	4.500	0.52027	
				Iron	7439-89-6	0.005	0.00041	
				Lead	7439-92-1	0.005	0.00060	
				Zinc	7440-66-6	0.003	0.00023	
				Phosphorous	7723-14-0	0.002	0.00005	
4	Electrodes	Copper Alloy	0.0135	Copper	7440-50-8	95.485	3.87348	4.098
				Silver	7440-22-4	4.500	0.22411	
				Iron	7439-89-6	0.005	0.00018	
				Lead	7439-92-1	0.005	0.00026	
				Zinc	7440-66-6	0.003	0.00010	
				Phosphorous	7723-14-0	0.002	0.00002	
5	Chip	Silicon	0.0091	Silicon	7440-21-3	91.756	2.54003	2.768
				Nickel	7440-02-0	4.577	0.12670	
				Aluminum	7429-90-5	3.554	0.09838	
				Gold	7440-57-5	0.113	0.00314	
6	Solder Paste	Solder	0.0061	Lead*	7439-92-1	92.500	1.74946	1.855
				Tin	7440-31-5	5.000	0.06029	
				Silver	7440-22-4	2.500	0.04542	
7	Terminal Finish	Tin	0.0029	Tin	7440-31-5	100.000	0.86352	0.864
		Total weight	0.3302					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)